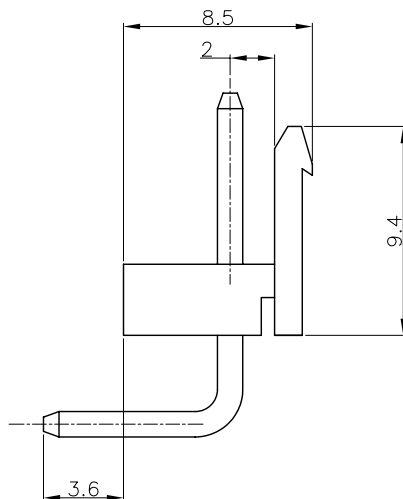
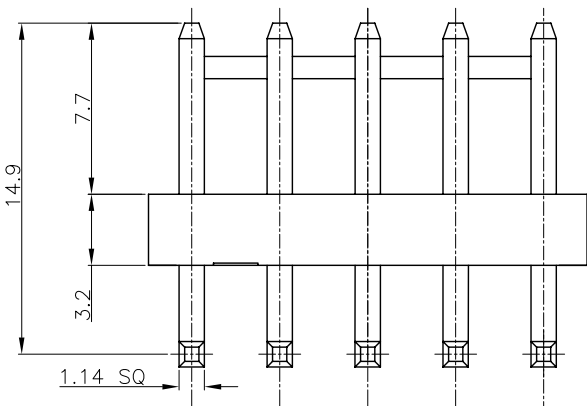
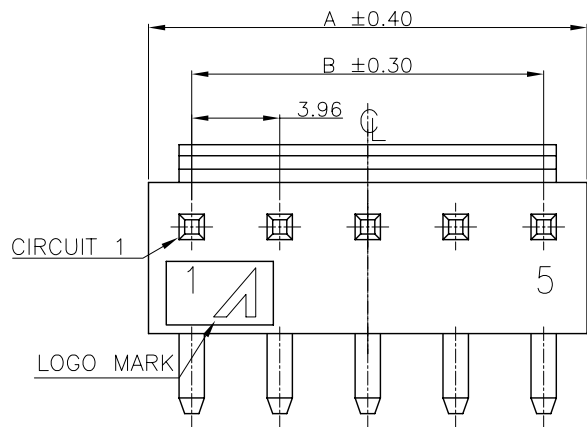


NOTES:

1. MATERIAL:

1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,
UL94V-0;

1.2 CONTACT: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

N: 50~100u" PURE TIN PLATING OVERALL

50u" MIN. NICKEL UNDERPLATING OVERALL

3. SPEC. PLS. REFER TO PS-51281-xxxxx-xxx

4. PART NUMBER

51318-XXX X X-XXX

NO OF CKT

PACKING

3:BAG

PLATING

L: PURE TIN PLATING

XXX	HOUSING MATERIAL	HALOGEN FREE
001	PA66 PLASTIC	HF

CKT	Dim A	Dim B
2	7.86	3.96
3	11.82	7.92
5	19.74	15.84

一般公差 TOLERANCES X ±0.5 .XX ±0.15 X ±0.25 .XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.					
檢驗尺寸標示 SYMBOLS ② ④ INDICATE CLASSIFICATION DIMENSION ② MARK IS CRITICAL DIM. ④ MARK IS MAJOR DIM.	品名 (TITLE) 3.96mm WTB Wafer Conn T/H S/R R/A Type		製圖 (DR) WESLEY 17/05/20		審核 (CHKD) ANDREW		
	圖號 (DWG NO.) 51318-XXXXX-XXX		核准 (APPD) CHARLESLEE				
	表面處理 (FINISH) _____		比例 (SCALE) 3:1	單位 (UNITS) mm		張數 (SHEET) 1 OF 1	SIZE A4